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AMENDMENTS TO THE CLAIMS

This listing of claims will replace all prior versions, and listings, of claims in the application:

Claim 1 (currently amended): A semiconductor laser device, comprising:

a first lead portion having a mounting portion on which a semiconductor laser chip is mounted;

a second lead portion for an electrode;

a third lead portion having a first side portion and a second side portion, the first side portion disposed to one side of the second lead portion and the second side portion disposed to another side of the second lead portion; and

a resin portion fixing said first, ~~[[and]]~~ second and third lead portions;

said second lead portion being provided with an engagement portion engaging with said resin portion in a longitudinal direction of said second lead portion, and extending straight within said resin portion.

Claim 2 (original): The semiconductor laser device according to claim 1, wherein said engagement portion includes a wide portion formed by locally expanding a width of said second lead portion within said resin portion.

Claim 3 (currently amended): The semiconductor laser device according to claim 1, comprising wherein:

said [[a]] third lead portion for heat radiation extending extends from said resin portion on a same side as said second lead portion ~~from said resin portion.~~

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Claim 4 (original): The semiconductor laser device according to claim 1, wherein an outer circumference of said resin portion has a circular shape with said semiconductor laser chip arranged at a center.

Claim 5 (original): The semiconductor laser device according to claim 1, wherein said resin portion has a window portion through which light emitted from said semiconductor laser chip passes.

Claim 6 (original): The semiconductor laser device according to claim 1, wherein an outer circumference of said resin portion is provided with a cut portion for stopping rotation.

Claim 7 (original): The semiconductor laser device according to claim 1, wherein said mounting portion in said first lead portion is made wider than said first lead portion excluding said mounting portion.

Claim 8 (currently amended): A semiconductor laser device, comprising:
a first lead portion having a mounting portion, on which a semiconductor laser chip is mounted, and a heat radiation portion extending from said mounting portion;
a second lead portion for an electrode, the second lead portion having a first side portion disposed to one side of said heat radiation portion and a second side portion disposed to another side of said heat radiation portion;
a third lead portion for heat radiation having a first side portion disposed to one side of said second lead portion and a second side portion disposed to another side of said second lead portion;
and
a resin portion fixing said first, second and third lead portions;

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wherein said second and third lead portions extend from said resin portion on a same side ~~from said~~ of the resin portion.

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